

**METHOD FOR FABRICATING TRANSISTORS HAVING  
DAMASCENE FORMED GATE CONTACTS AND  
SELF-ALIGNED BORDERLESS BIT LINE CONTACTS**

5     Abstract of the Invention

          A Dynamic Random Access Memory is fabricated in a semiconductor  
body of a first conductivity type in which there have been formed an array of  
memory cells which each include a trench capacitor and a vertical Insulated  
Gate Field Effect Transistor (IGFET). Each IGFET includes first and second  
10     output regions of a second opposite conductivity type and a gate which is  
separated from a surface of the semiconductor body by a gate dielectric layer. A  
gate electrode connected to the gate is formed using a Damascene process with  
insulating sidewall spacer regions being formed before the gate electrode is  
formed. Borderless contacts, which are self aligned, are made to the first output  
15     regions of each transistor using a Damascene process.